



**EXPEDITED PROCEDURE – EXAMINING GROUP 2814**

**S/N 09/733,289**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit:	2814
Filed:	December 8, 2000	Docket No.:	884.798US1
Title:	Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers		
Customer Number:	21186		

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**SUPPLEMENTAL RESPONSE UNDER 37 C.F.R. 1.116**

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Commissioner for Patents  
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This paper is in response to the Advisory Action mailed February 3, 2006, and is supplemental to the Response Under 37 CFR 1.116 filed January 5, 2006 in response to the Final Office Action mailed October 5, 2005. Please consider the remarks as follows: